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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, PWM, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	36 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc710-04i-ss

FIGURE 4-5: PIC16C711 REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h		PCON	87h
08h	ADCON0	ADCON1	88h
09h	ADRES	ADRES	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch–4Fh	General Purpose Register	General Purpose Register Mapped in Bank 0(2)	8Ch–CFh
50h–7Fh			D0h–FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

2: These locations are unimplemented in Bank 1. Any access to these locations will access the corresponding Bank 0 register.

FIGURE 4-6: PIC16C715 REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h–7Fh	General Purpose Register	General Purpose Register (A0h–BFh)	A0h–BFh
		(C0h–FFh)	C0h–FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

6.3 Prescaler

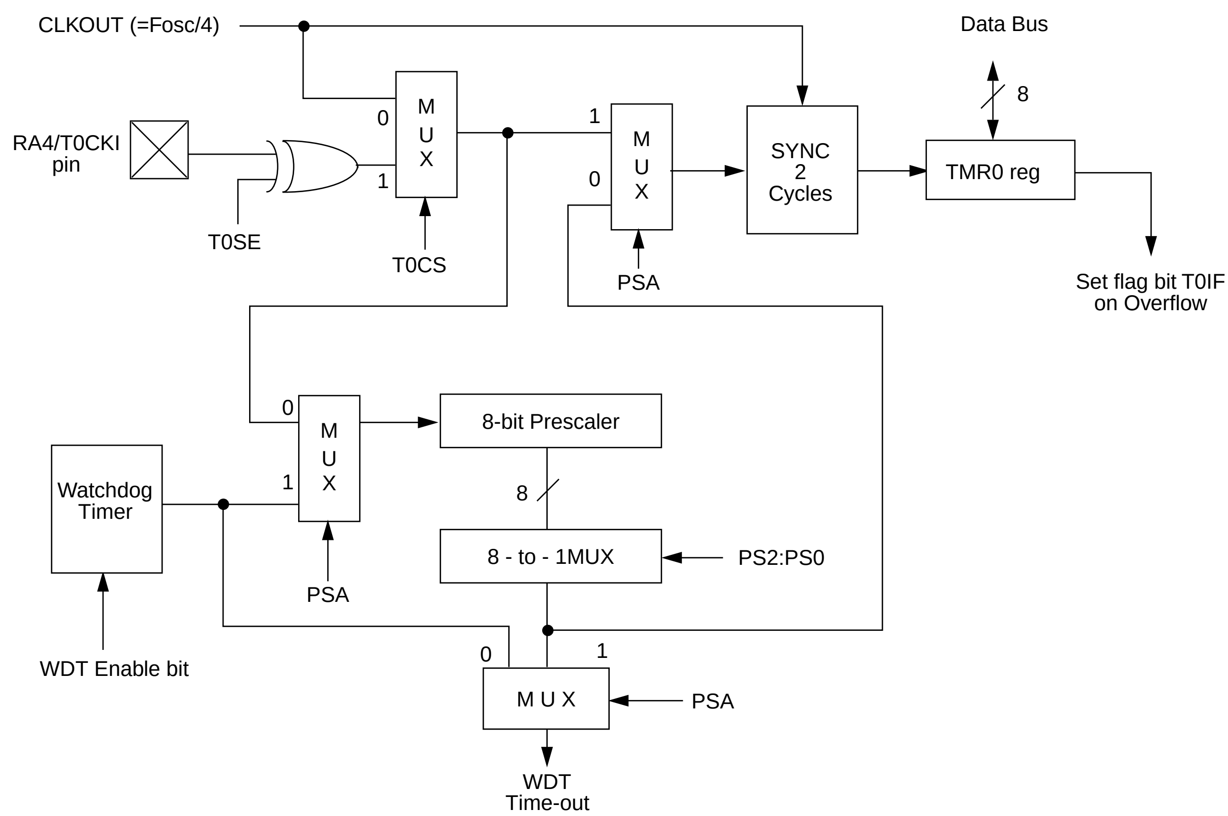
An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 6-6). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer, and vice-versa.

The PSA and PS2:PS0 bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g. `CLRF 1, MOVWF 1, BSF 1,x`....etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

Note:	Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.

FIGURE 6-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS2:PS0 are (OPTION<5:0>).

7.5 A/D Operation During Sleep

The A/D module can operate during SLEEP mode. This requires that the A/D clock source be set to RC (ADCS1:ADCS0 = 11). When the RC clock source is selected, the A/D module waits one instruction cycle before starting the conversion. This allows the SLEEP instruction to be executed, which eliminates all digital switching noise from the conversion. When the conversion is completed the GO/$\overline{\text{DONE}}$ bit will be cleared, and the result loaded into the ADRES register. If the A/D interrupt is enabled, the device will wake-up from SLEEP. If the A/D interrupt is not enabled, the A/D module will then be turned off, although the ADON bit will remain set.

When the A/D clock source is another clock option (not RC), a SLEEP instruction will cause the present conversion to be aborted and the A/D module to be turned off, though the ADON bit will remain set.

Turning off the A/D places the A/D module in its lowest current consumption state.

Note:	For the A/D module to operate in SLEEP, the A/D clock source must be set to RC (ADCS1:ADCS0 = 11). To perform an A/D conversion in SLEEP, ensure the SLEEP instruction immediately follows the instruction that sets the GO/$\overline{\text{DONE}}$ bit.

7.6 A/D Accuracy/Error

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at < ±1 LSb for $V_{DD} = V_{REF}$ (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as V_{DD} diverges from V_{REF}.

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically ± 1/2 LSb and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, T_{AD} should be derived from the device oscillator. T_{AD} must not violate the minimum and should be ≤ 8 µs for preferred operation. This is because T_{AD}, when derived from T_{OSC}, is kept away from on-chip phase clock transitions. This reduces, to a large extent, the effects of digital switching noise. This is not possible with the RC derived clock. The loss of accuracy due to digital switching noise can be significant if many I/O pins are active.

In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

7.7 Effects of a RESET

A device reset forces all registers to their reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The value that is in the ADRES register is not modified for a Power-on Reset. The ADRES register will contain unknown data after a Power-on Reset.

7.8 Connection Considerations

If the input voltage exceeds the rail values (V_{SS} or V_{DD}) by greater than 0.2V, then the accuracy of the conversion is out of specification.

Note:	Care must be taken when using the RA0 pin in A/D conversions due to its proximity to the OSC1 pin.

An external RC filter is sometimes added for anti-aliasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 kΩ recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

TABLE 7-3: REGISTERS/BITS ASSOCIATED WITH A/D, PIC16C710/71/711

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh	INTCON	GIE	ADIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
89h	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
08h	ADCON0	ADCS1	ADCS0	—	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADIF	ADON	00-0 0000	00-0 0000
88h	ADCON1	—	—	—	—	—	—	PCFG1	PCFG0	---- --00	---- --00
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	---x 0000	---u 0000
85h	TRISA	—	—	—	PORTA Data Direction Register					---1 1111	---1 1111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D conversion.

TABLE 7-4: REGISTERS/BITS ASSOCIATED WITH A/D, PIC16C715

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	—	—	—	-0-- ----	-0-- ----
8Ch	PIE1	—	ADIE	—	—	—	—	—	—	-0-- ----	-0-- ----
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON	0000 00-0	0000 00-0
9Fh	ADCON1	—	—	—	—	—	—	PCFG1	PCFG0	---- --00	---- --00
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	---x 0000	---u 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D conversion.

8.5 Interrupts

Applicable Devices	710	71	711	715

The PIC16C71X family has 4 sources of interrupt.

Interrupt Sources
External interrupt RB0/INT
TMR0 overflow interrupt
PORTB change interrupts (pins RB7:RB4)
A/D Interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

> **Note:** Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 8-19). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

> **Note:** For the PIC16C71
> If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:
>
> 1. An instruction clears the GIE bit while an interrupt is acknowledged.
> 2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
> 3. The Interrupt Service Routine completes with the execution of the RETFIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.
>
> Perform the following to ensure that interrupts are globally disabled:

```
LOOP BCF   INTCON, GIE  ; Disable global
                        ;  interrupt bit
     BTFSC INTCON, GIE  ; Global interrupt
                        ;   disabled?
     GOTO  LOOP         ; NO, try again
        :               ;   Yes, continue
                        ;   with program
                        ;   flow
```

8.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if bit INTEDG (OPTION<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 8.8 for details on SLEEP mode.

8.5.2 TMR0 INTERRUPT

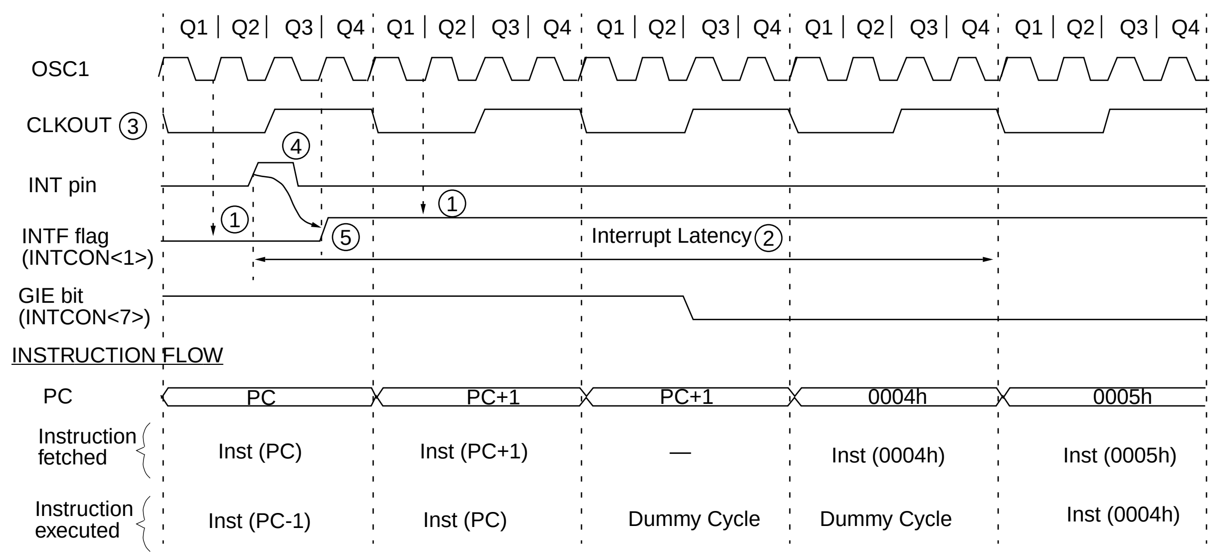
An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 6.0)

8.5.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 5.2)

Note:	For the PIC16C71 if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

FIGURE 8-19: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).
2: Interrupt latency = 3-4 Tcy where Tcy = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.
3: CLKOUT is available only in RC oscillator mode.
4: For minimum width of INT pulse, refer to AC specs.
5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

NOTES:

CLRF — Clear f

Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 127$
Operation:	$00h \rightarrow (f)$ $1 \rightarrow Z$
Status Affected:	Z
Encoding:	`00` `0001` `1fff` `ffff`
Description:	The contents of register 'f' are cleared and the Z bit is set.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write register 'f'

Example `CLRF FLAG_REG`

Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW — Clear W

Syntax:	[*label*] CLRW
Operands:	None
Operation:	$00h \rightarrow (W)$ $1 \rightarrow Z$
Status Affected:	Z
Encoding:	`00` `0001` `0xxx` `xxxx`
Description:	W register is cleared. Zero bit (Z) is set.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	NOP	Process data	Write to W

Example `CLRW`

Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT — Clear Watchdog Timer

Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	$00h \rightarrow WDT$ $0 \rightarrow$ WDT prescaler, $1 \rightarrow \overline{TO}$ $1 \rightarrow \overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Encoding:	`00` `0000` `0110` `0100`
Description:	`CLRWDT` instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.
Words:	1
Cycles:	1

Q Cycle Activity:

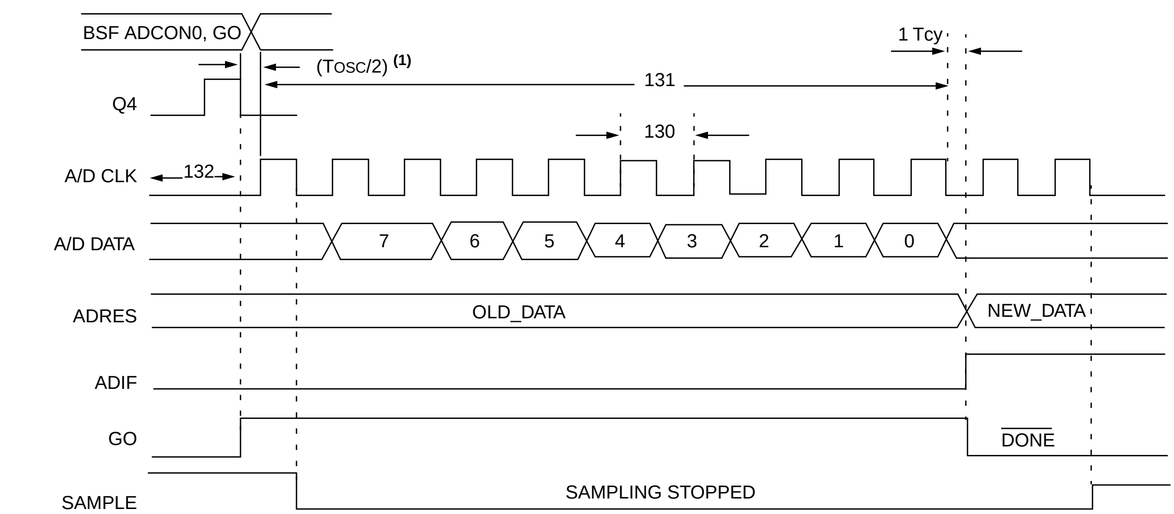
Q1	Q2	Q3	Q4
Decode	NOP	Process data	Clear WDT Counter

Example `CLRWDT`

Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

Applicable Devices	710	71	711	715

FIGURE 11-7: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 11-7: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16**C**710/711	1.6	—	—	µs	TOSC based, VREF ≥ 3.0V
			PIC16**LC**710/711	2.0	—	—	µs	TOSC based, VREF full range
			PIC16**C**710/711	2.0*	4.0	6.0	µs	A/D RC mode
			PIC16**LC**710/711	3.0*	6.0	9.0	µs	A/D RC mode
131	TCNV	Conversion time (not including S/H time). (Note 1)		—	9.5	—	TAD	
132	TACQ	Acquisition time		Note 2	20	—	µs	
				5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 19.5 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	TGO	Q4 to AD clock start		—	TOSC/2§	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	TSWC	Switching from convert → sample time		1.5§	—	—	TAD	

* These parameters are characterized but not tested.
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
§ This specification ensured by design.
Note 1: ADRES register may be read on the following TCY cycle.
2: See Section 7.1 for min conditions.

Applicable Devices	710	71	711	715

FIGURE 12-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

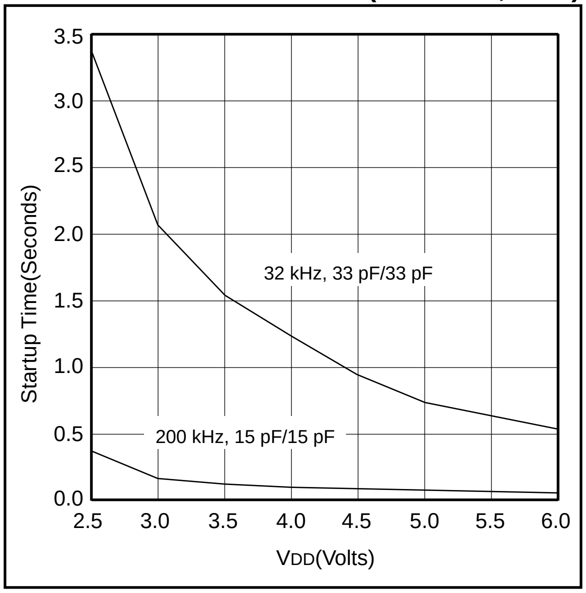


FIGURE 12-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)

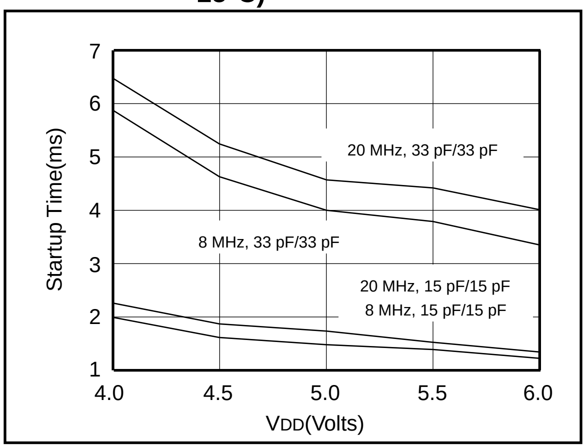


FIGURE 12-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

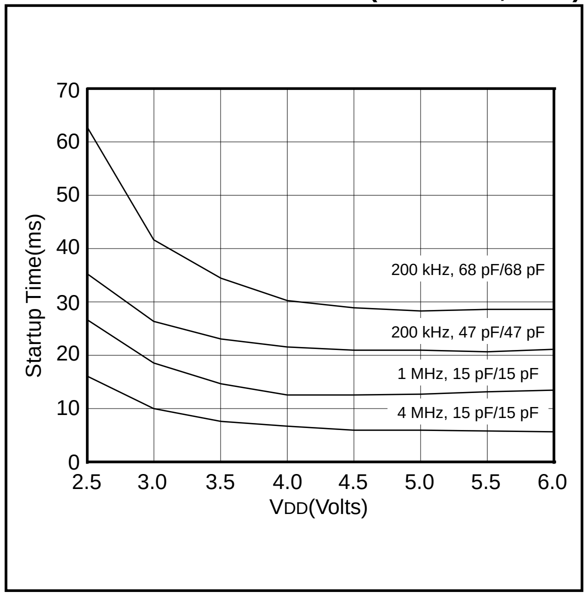


TABLE 12-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
Crystals Used			
32 kHz	Epson C-001R32.768K-A		± 20 PPM
200 kHz	STD XTL 200.000KHz		± 20 PPM
1 MHz	ECS ECS-10-13-1		± 50 PPM
4 MHz	ECS ECS-40-20-1		± 50 PPM
8 MHz	EPSON CA-301 8.000M-C		± 30 PPM
20 MHz	EPSON CA-301 20.000M-C		± 30 PPM

Applicable Devices	710	71	711	715

13.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

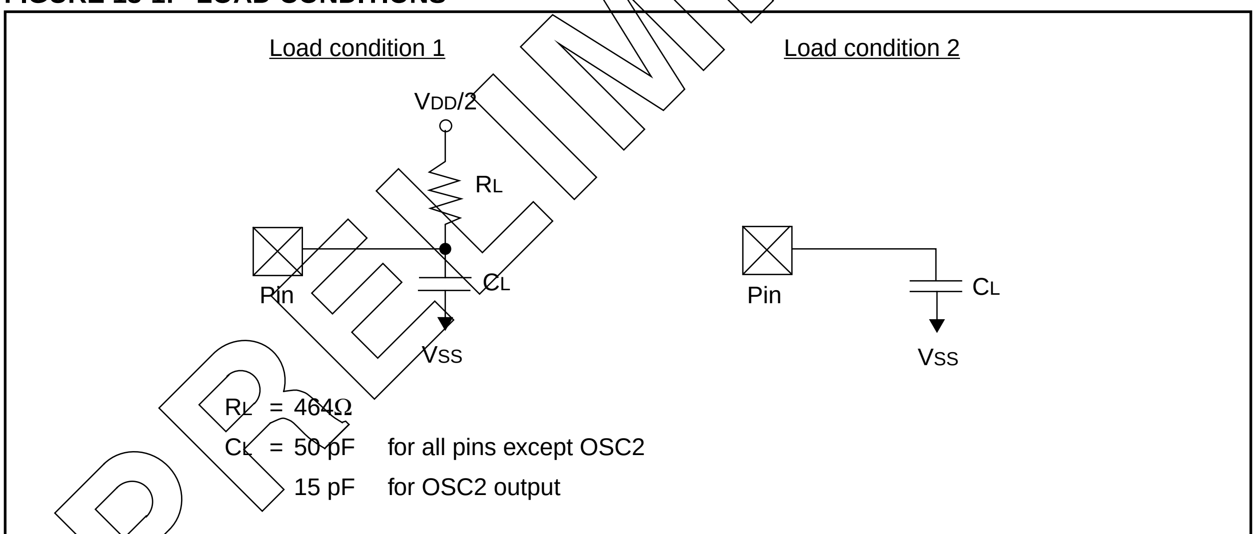
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{\text{RD}}$
cs	$\overline{\text{CS}}$	rw	$\overline{\text{RD}}$ or $\overline{\text{WR}}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{\text{SS}}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{\text{MCLR}}$	wr	$\overline{\text{WR}}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance

FIGURE 13-1: LOAD CONDITIONS



Applicable Devices	710	71	711	715

13.5 Timing Diagrams and Specifications

FIGURE 13-2: EXTERNAL CLOCK TIMING

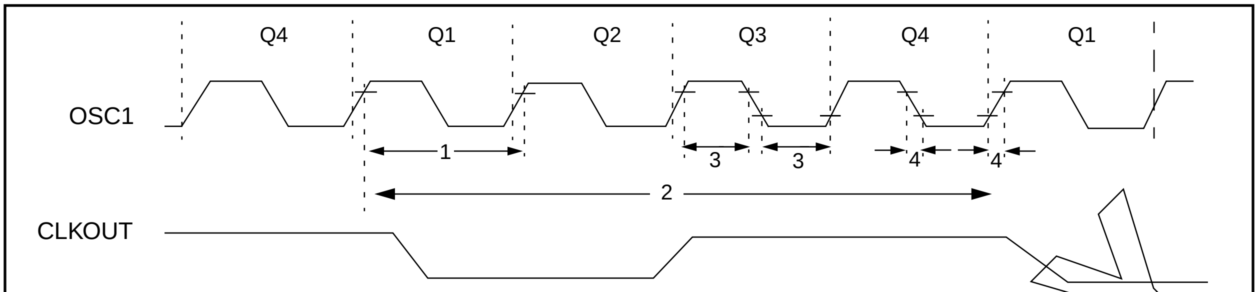


TABLE 13-2: CLOCK TIMING REQUIREMENTS

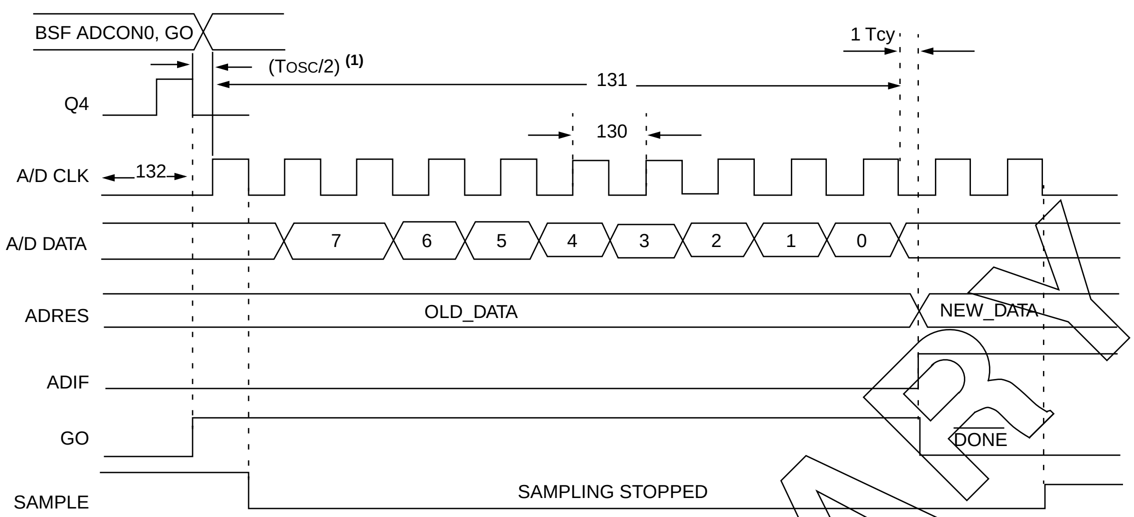
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fos	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT osc mode
			DC	—	4	MHz	HS osc mode (PIC16C715-04)
			DC	—	20	MHz	HS osc mode (PIC16C715-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	4	MHz	HS osc mode (PIC16C715-04)
			4	—	10	MHz	HS osc mode (PIC16C715-10)
			4	—	20	MHz	HS osc mode (PIC16C715-20)
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (PIC16C715-04)
			100	—	—	ns	HS osc mode (PIC16C715-10)
			50	—	—	ns	HS osc mode (PIC16C715-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (PIC16C715-04)
			100	—	250	ns	HS osc mode (PIC16C715-10)
			50	—	250	ns	HS osc mode (PIC16C715-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	—	DC	ns	TCY = 4/FOSC
3	TosL, TosH	**External Clock in (OSC1) High or Low Time**	50	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			10	—	—	ns	HS oscillator
4	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C715.

Applicable Devices	710	71	711	715

FIGURE 13-7: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 13-8: A/D CONVERSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	1.6 2.0		— —	µs µs	VREF ≥ 3.0V VREF full range
130	TAD	A/D Internal RC Oscillator source					ADCS1:ADCS0 = 11 (RC oscillator source)
			3.0	6.0	9.0	µs	PIC16LC715, VDD = 3.0V
			2.0	4.0	6.0	µs	PIC16C715
131	TCNV	Conversion time (not including S/H time). Note 1	—	9.5TAD	—	—	
132	TACQ	Acquisition time	Note 2	20	—	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

Applicable Devices	710	71	711	715

FIGURE 14-14: TYPICAL IDD vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

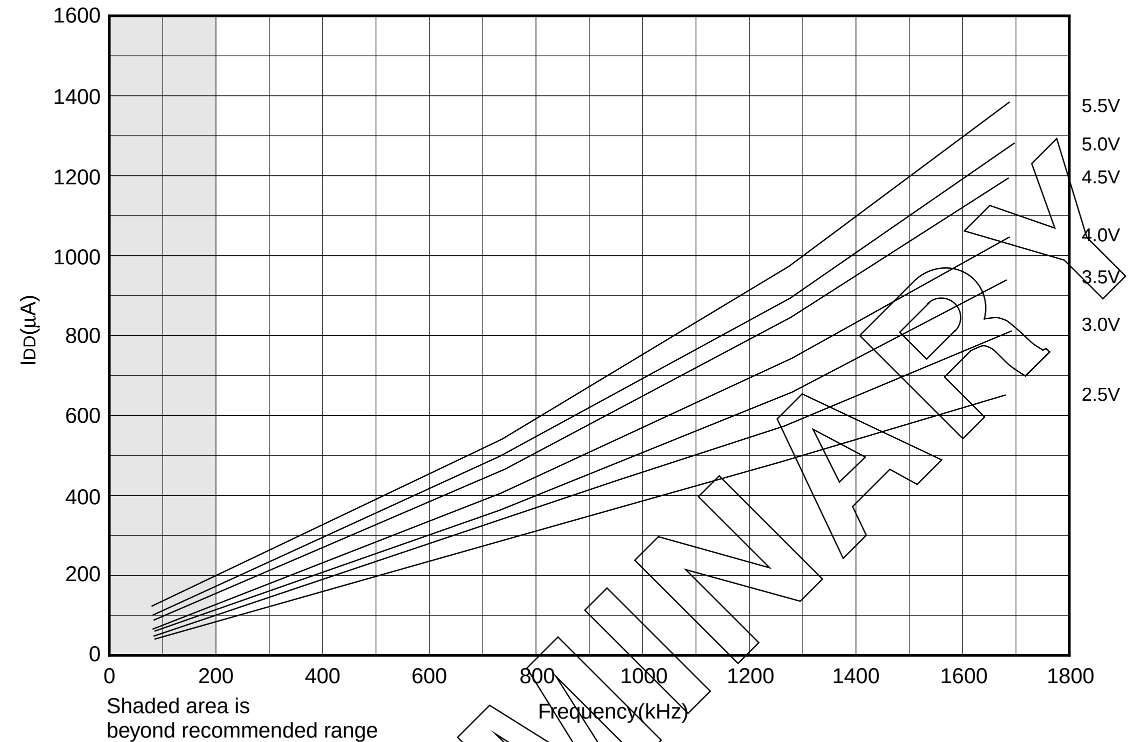
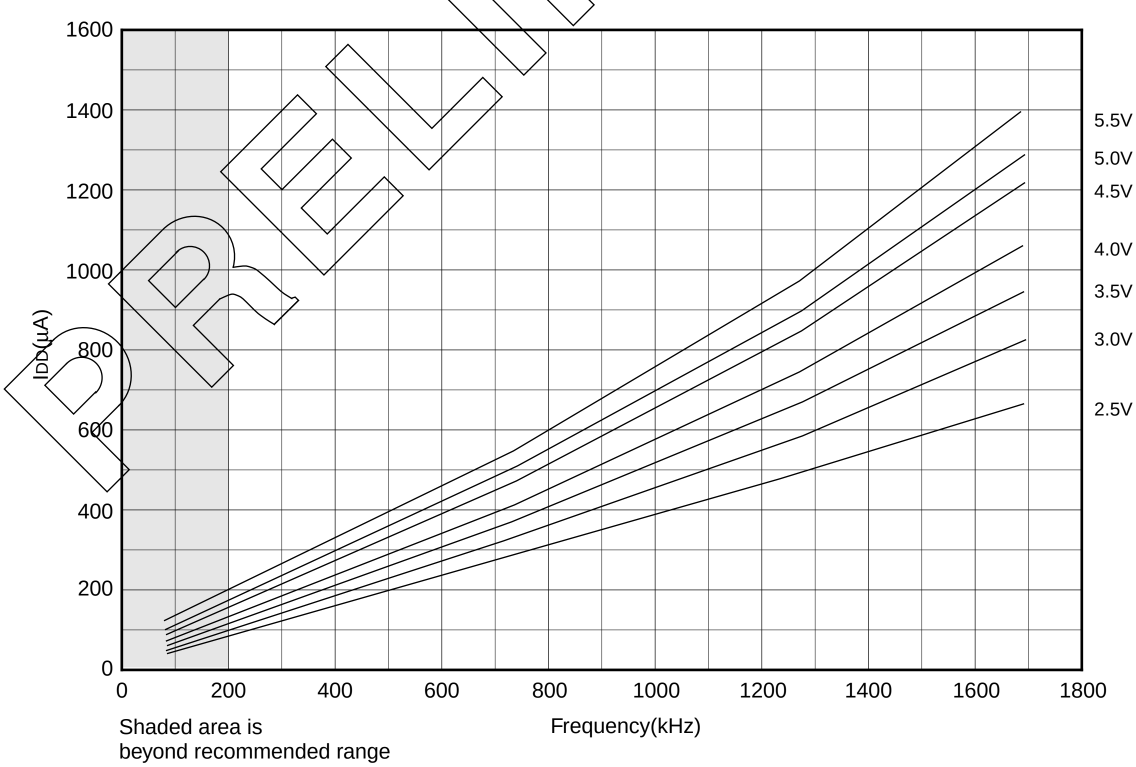


FIGURE 14-15: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)



Applicable Devices	710	71	711	715

FIGURE 14-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

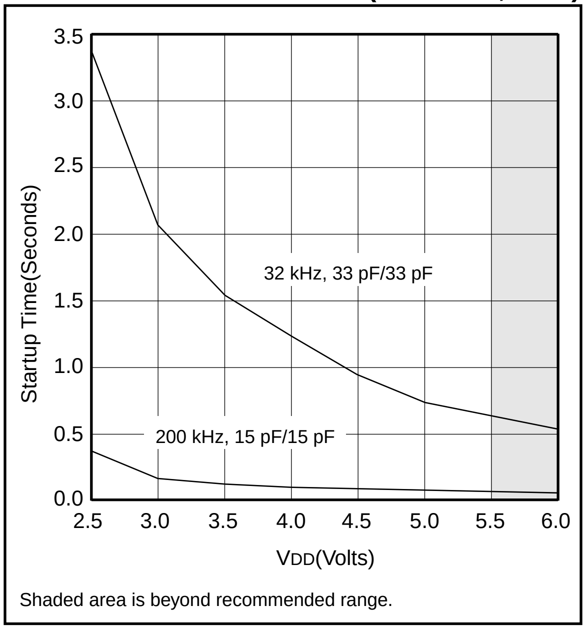


FIGURE 14-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)

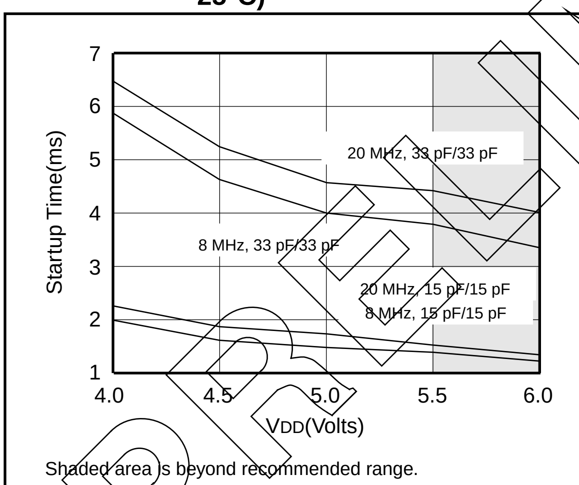


FIGURE 14-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

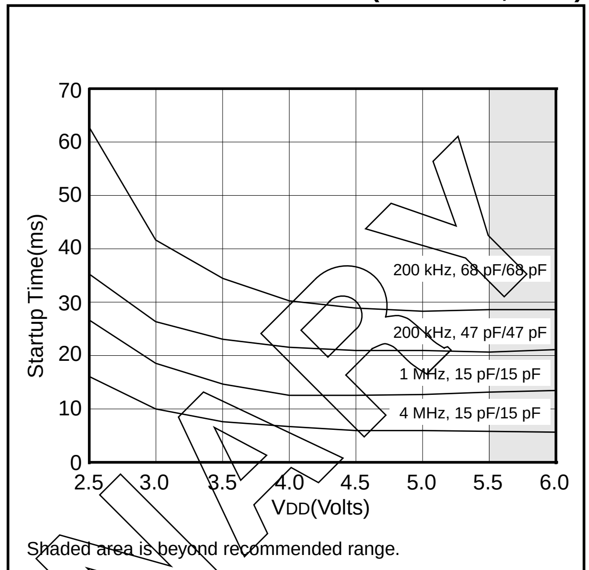


TABLE 14-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	**Crystal Freq**	**Cap. Range C1**	**Cap. Range C2**
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
Crystals Used			
32 kHz	Epson C-001R32.768K-A		± 20 PPM
200 kHz	STD XTL 200.000KHz		± 20 PPM
1 MHz	ECS ECS-10-13-1		± 50 PPM
4 MHz	ECS ECS-40-20-1		± 50 PPM
8 MHz	EPSON CA-301 8.000M-C		± 30 PPM
20 MHz	EPSON CA-301 20.000M-C		± 30 PPM

Applicable Devices	710	71	711	715

15.3 DC Characteristics: PIC16C71-04 (Commercial, Industrial) PIC16C71-20 (Commercial, Industrial) PIC16LC71-04 (Commercial, Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) OOperating temperature 0˚C ≤ TA ≤ +70˚C (commercial) -40˚C ≤ TA ≤ +85˚C (industrial) Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	V_{IL}					
D030	with TTL buffer		V_{SS}	-	0.15V	V	For entire V_{DD} range
D031	with Schmitt Trigger buffer		V_{SS}	-	0.8V	V	$4.5 \leq V_{DD} \leq 5.5V$
D032	$\overline{MCLR}$, OSC1 (in RC mode)		V_{SS}	-	$0.2V_{DD}$	V	
D033	OSC1 (in XT, HS and LP)		V_{SS}	-	$0.3V_{DD}$	V	Note1
	Input High Voltage						
	I/O ports (Note 4)	V_{IH}		-			
D040	with TTL buffer		2.0	-	V_{DD}	V	$4.5 \leq V_{DD} \leq 5.5V$
D040A			$0.25V_{DD}$ + 0.8V	-	V_{DD}		For entire V_{DD} range
D041	with Schmitt Trigger buffer		$0.85V_{DD}$	-	V_{DD}		For entire V_{DD} range
D042	$\overline{MCLR}$, RB0/INT		$0.85V_{DD}$	-	V_{DD}	V	
D042A	OSC1 (XT, HS and LP)		$0.7V_{DD}$	-	V_{DD}	V	Note1
D043	OSC1 (in RC mode)		$0.9V_{DD}$	-	V_{DD}	V	
D070	PORTB weak pull-up current	I_{PURB}	50	250	†400	μA	V_{DD} = 5V, V_{PIN} = V_{SS}
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	I_{IL}	-	-	±1	μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$
D063	OSC1		-	-	±5	μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	V_{OL}	-	-	0.6	V	I_{OL} = 8.5mA, V_{DD} = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	I_{OL} = 1.6mA, V_{DD} = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	V_{OH}	V_{DD} - 0.7	-	-	V	I_{OH} = -3.0mA, V_{DD} = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		V_{DD} - 0.7	-	-	V	I_{OH} = -1.3mA, V_{DD} = 4.5V, -40°C to +85°C
D130*	**Open-Drain High Voltage**	V_{OD}	-	-	14	V	RA4 pin

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC16C71 be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: PIC16C71 Rev. "Ax" INT pin has a TTL input buffer. PIC16C71 Rev. "Bx" INT pin has a Schmitt Trigger input buffer.

Applicable Devices	710	71	711	715

FIGURE 16-12: TYPICAL IDD VS. FREQ (EXT CLOCK, 25°C)

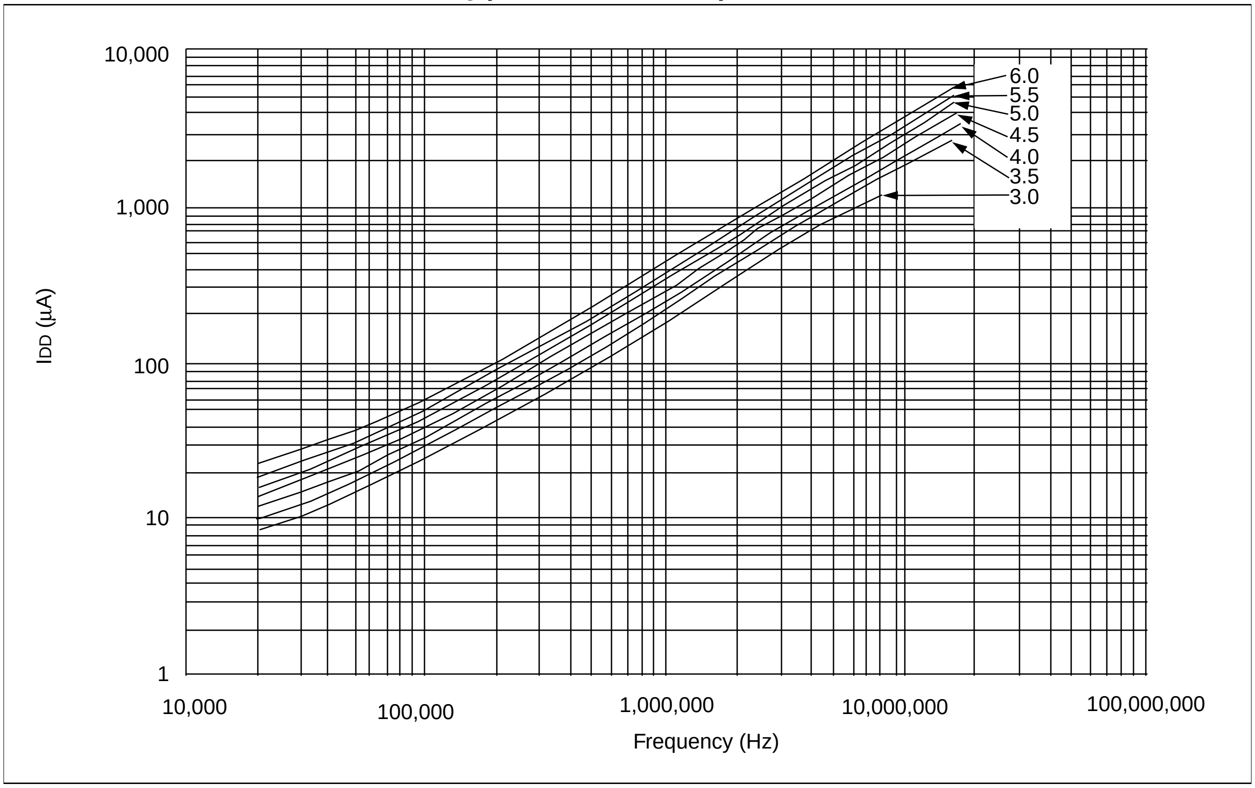
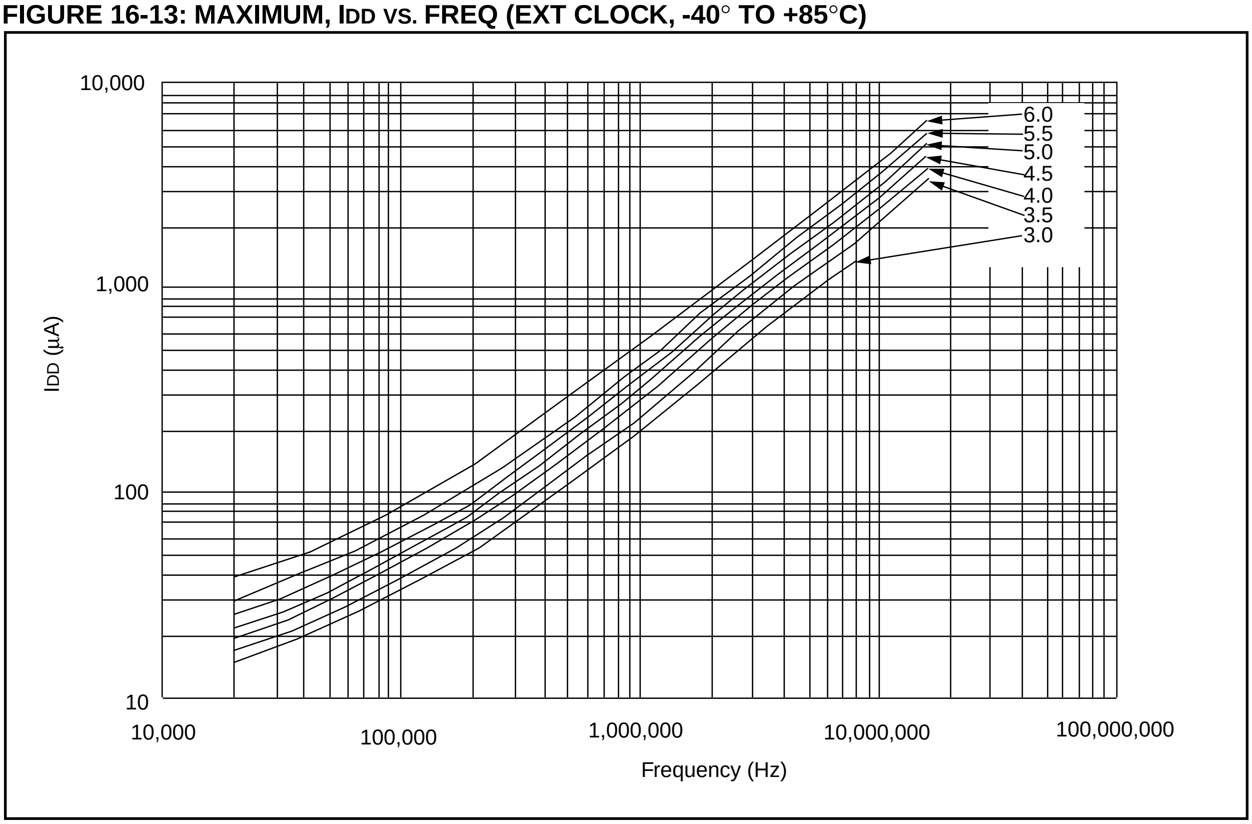


FIGURE 16-13: MAXIMUM, IDD VS. FREQ (EXT CLOCK, -40° TO +85°C)



Data based on matrix samples. See first page of this section for details.

APPENDIX C: WHAT'S NEW

1. Consolidated all pin compatible 18-pin A/D based devices into one data sheet.

APPENDIX D: WHAT'S CHANGED

1. Minor changes, spelling and grammatical changes.
2. Low voltage operation on the PIC16LC710/711/715 has been reduced from 3.0V to 2.5V.
3. Part numbers of the PIC16C70 and PIC16C71A have changed to PIC16C710 and PIC16C711, respectively.

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- The PICmicro family meets the specifications contained in the Microchip Data Sheet.
- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable”.
- Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our product.

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